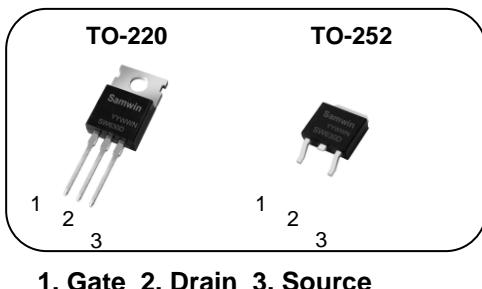
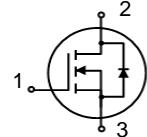


**N-channel Enhanced mode TO-220/TO-252 MOSFET****Features**

- High ruggedness
- Low  $R_{DS(ON)}$  (Typ 0.27Ω)@ $V_{GS}=10V$
- Low Gate Charge (Typ 20nC)
- Improved dv/dt Capability
- 100% Avalanche Tested
- Application:Synchronous Rectification, DC-DC

 **$BV_{DSS}$  : 200V** **$I_D$  : 9A** **$R_{DS(ON)}$  : 0.27Ω****General Description**

This power MOSFET is produced with advanced technology of SAMWIN.

This technology enable the power MOSFET to have better characteristics, including fast switching time, low on resistance, low gate charge and especially excellent avalanche characteristics.

**Order Codes**

Item	Sales Type	Marking	Package	Packaging
1	SW P 630D	SW630D	TO-220	TUBE
2	SW D 630D	SW630D	TO-252	REEL

**Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		TO-220	TO-252	
$V_{DSS}$	Drain to source voltage	200		V
$I_D$	Continuous drain current (@ $T_C=25^\circ C$ )	9*		A
	Continuous drain current (@ $T_C=100^\circ C$ )	5.7*		A
$I_{DM}$	Drain current pulsed (note 1)	36		A
$V_{GS}$	Gate to source voltage	±20		V
$E_{AS}$	Single pulsed avalanche energy (note 2)	156		mJ
$E_{AR}$	Repetitive avalanche energy (note 1)	16		mJ
dv/dt	Peak diode recovery dv/dt (note 3)	5		V/ns
$P_D$	Total power dissipation (@ $T_C=25^\circ C$ )	138.9	96.2	W
	Derating factor above 25°C	1.1	0.8	W/°C
$T_{STG}, T_J$	Operating junction temperature & storage temperature	-55 ~ + 150		°C
$T_L$	Maximum lead temperature for soldering purpose, 1/8 from case for 5 seconds.	300		°C

\*. Drain current is limited by junction temperature.

**Thermal characteristics**

Symbol	Parameter	Value		Unit
		TO-220	TO-252	
$R_{thjc}$	Thermal resistance, Junction to case	0.9	1.3	°C/W
$R_{thja}$	Thermal resistance, Junction to ambient	54		°C/W

### Electrical characteristic ( $T_C = 25^\circ\text{C}$ unless otherwise specified )

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
<b>Off characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain to source breakdown voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	200			V
$\Delta \text{BV}_{\text{DSS}} / \Delta T_J$	Breakdown voltage temperature coefficient	$I_{\text{D}}=250\mu\text{A}$ , referenced to $25^\circ\text{C}$		0.23		$^\circ\text{C}$
$I_{\text{DSS}}$	Drain to source leakage current	$V_{\text{DS}}=200\text{V}, V_{\text{GS}}=0\text{V}$			1	$\mu\text{A}$
		$V_{\text{DS}}=160\text{V}, T_C=125^\circ\text{C}$			50	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to source leakage current, forward	$V_{\text{GS}}=20\text{V}, V_{\text{DS}}=0\text{V}$			100	nA
	Gate to source leakage current, reverse	$V_{\text{GS}}=-20\text{V}, V_{\text{DS}}=0\text{V}$			-100	nA
<b>On characteristics</b>						
$V_{\text{GS(TH)}}$	Gate threshold voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2		4	V
$R_{\text{DS(ON)}}$	Drain to source on state resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=4.5\text{A}$		0.27	0.4	$\Omega$
$G_{\text{fs}}$	Forward transconductance	$V_{\text{DS}}=20\text{V}, I_{\text{D}}=4.5\text{A}$		6.2		S
<b>Dynamic characteristics</b>						
$C_{\text{iss}}$	Input capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, f=1\text{MHz}$		720		pF
$C_{\text{oss}}$	Output capacitance			117		
$C_{\text{rss}}$	Reverse transfer capacitance			30		
$t_{\text{d(on)}}$	Turn on delay time	$V_{\text{DS}}=100\text{V}, I_{\text{D}}=9\text{A}, R_G=25\Omega, V_{\text{GS}}=10\text{V}$ (note 4,5)		7		ns
$t_r$	Rising time			33		
$t_{\text{d(off)}}$	Turn off delay time			41		
$t_f$	Fall time			29		
$Q_g$	Total gate charge			20		nC
$Q_{\text{gs}}$	Gate-source charge	$V_{\text{DS}}=160\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=9\text{A}$ $I_{\text{g}}=13\text{mA}$		4		
$Q_{\text{gd}}$	Gate-drain charge			8		
$R_g$	Gate resistance	$V_{\text{DS}}=0\text{V}$ , Scan F mode		1.9		$\Omega$

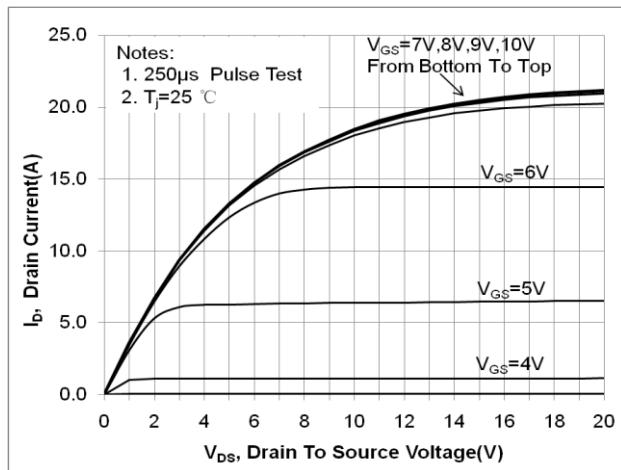
### Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			9	A
$I_{\text{SM}}$	Pulsed source current				36	A
$V_{\text{SD}}$	Diode forward voltage drop.	$I_s=9\text{A}, V_{\text{GS}}=0\text{V}$			1.4	V
$t_{\text{rr}}$	Reverse recovery time	$I_s=9\text{A}, V_{\text{GS}}=0\text{V}, dI_F/dt=100\text{A/us}$		128		ns
$Q_{\text{rr}}$	Reverse recovery charge			556		nC

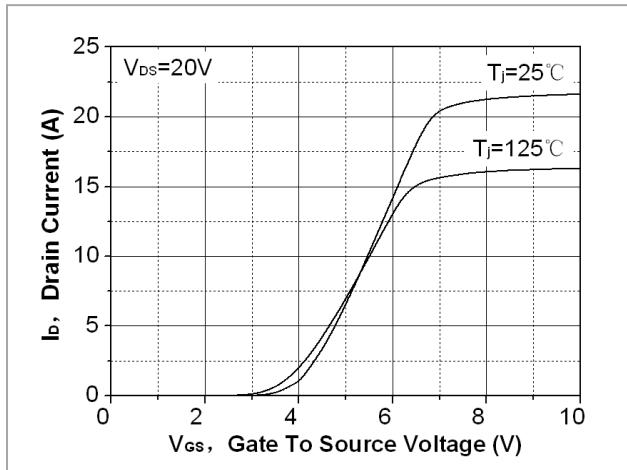
#### ※ Notes

- Repetitive rating : pulse width limited by junction temperature.
- $L = 3.85\text{mH}, I_{\text{AS}} = 9\text{A}, V_{\text{DD}} = 50\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
- $I_{\text{SD}} \leq 9\text{A}, dI/dt = 100\text{A/us}, V_{\text{DD}} \leq \text{BV}_{\text{DSS}}$ , Starting  $T_J = 25^\circ\text{C}$
- Pulse Test : Pulse Width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
- Essentially independent of operating temperature.

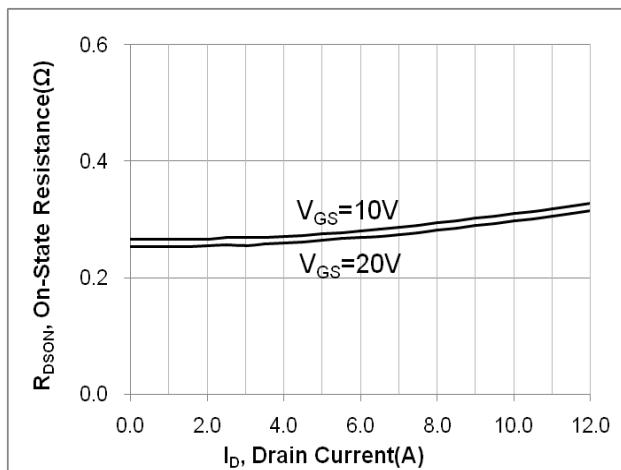
**Fig. 1. On-state characteristics**



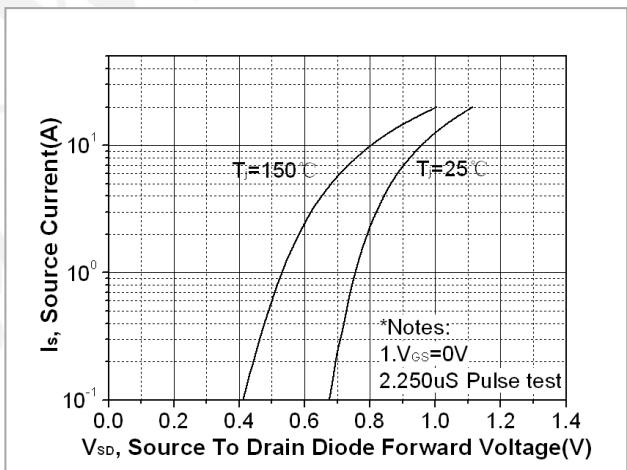
**Fig. 2. Transfer characteristics**



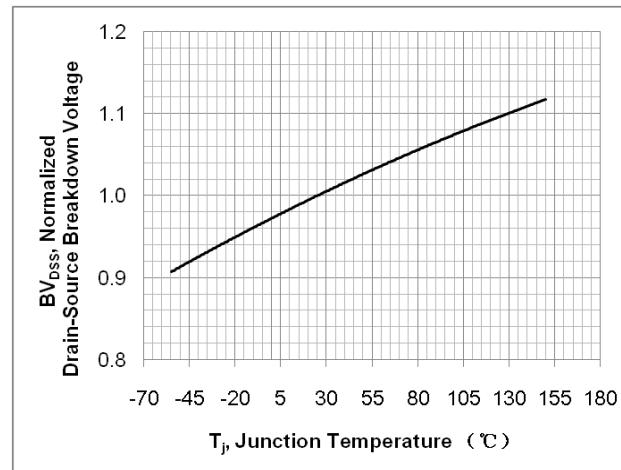
**Fig. 3. On-resistance variation vs. drain current and gate voltage**



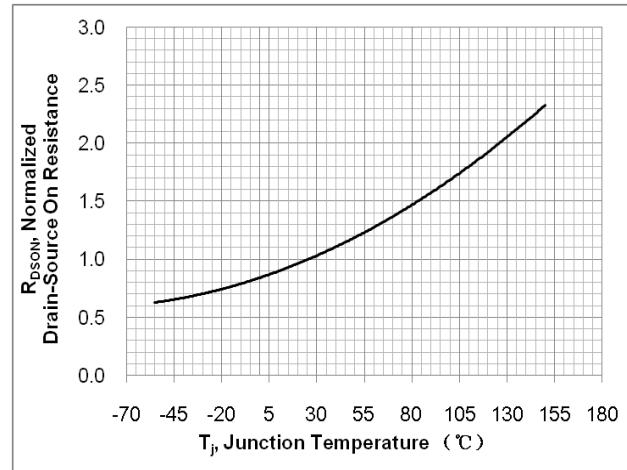
**Fig. 4. On-state current vs. diode forward voltage**



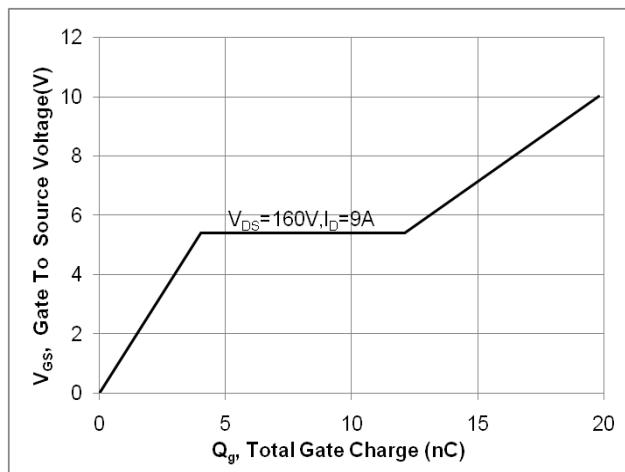
**Fig. 5. Breakdown voltage variation vs. junction temperature**



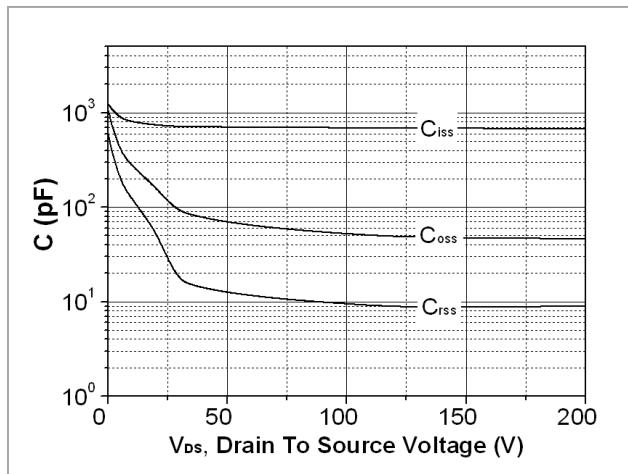
**Fig. 6. On-resistance variation vs. junction temperature**



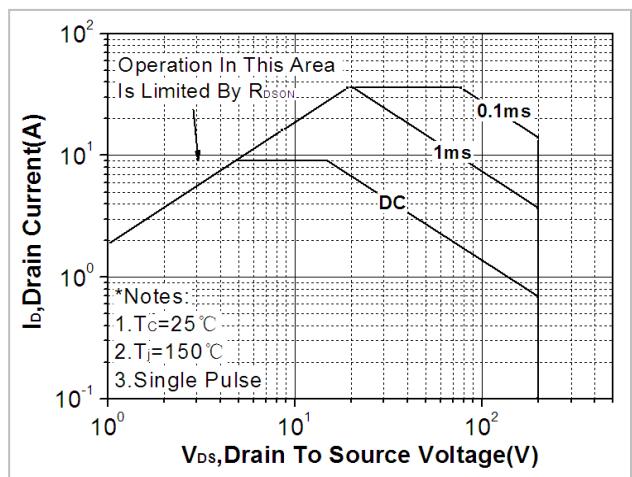
**Fig. 7. Gate charge characteristics**



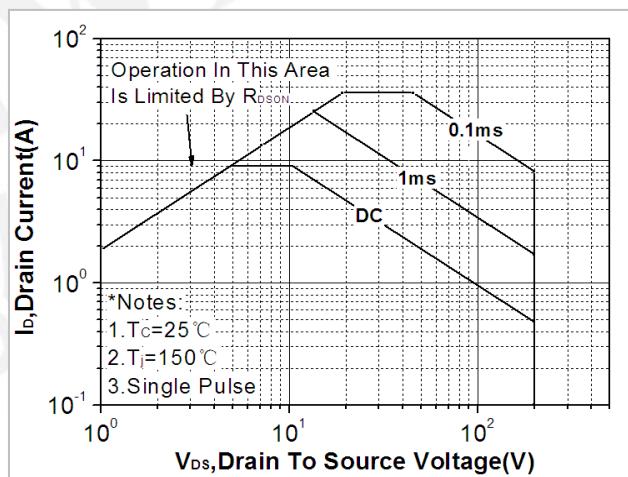
**Fig. 8. Capacitance Characteristics**



**Fig. 9. Maximum safe operating area(TO-220)**



**Fig. 10. Maximum safe operating area(TO-252)**



**Fig. 11. Transient thermal response curve(TO-220)**

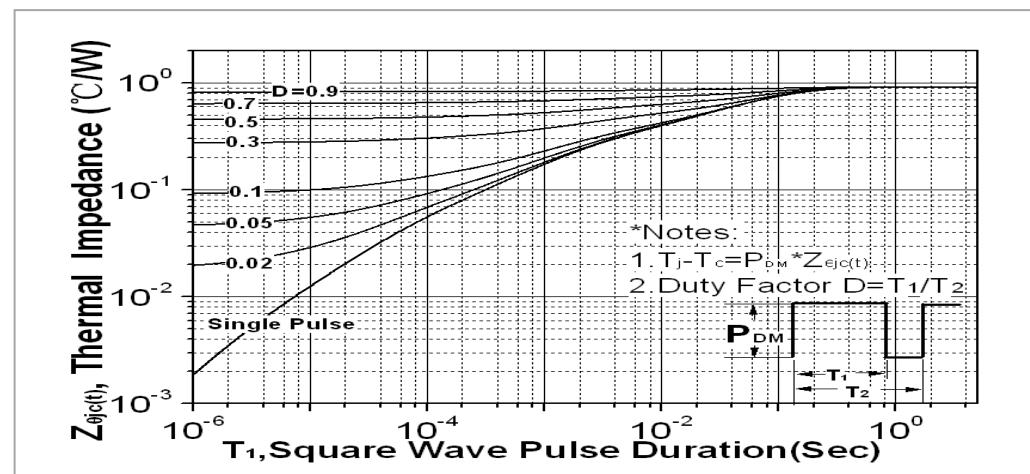


Fig. 12. Transient thermal response curve(TO-252)

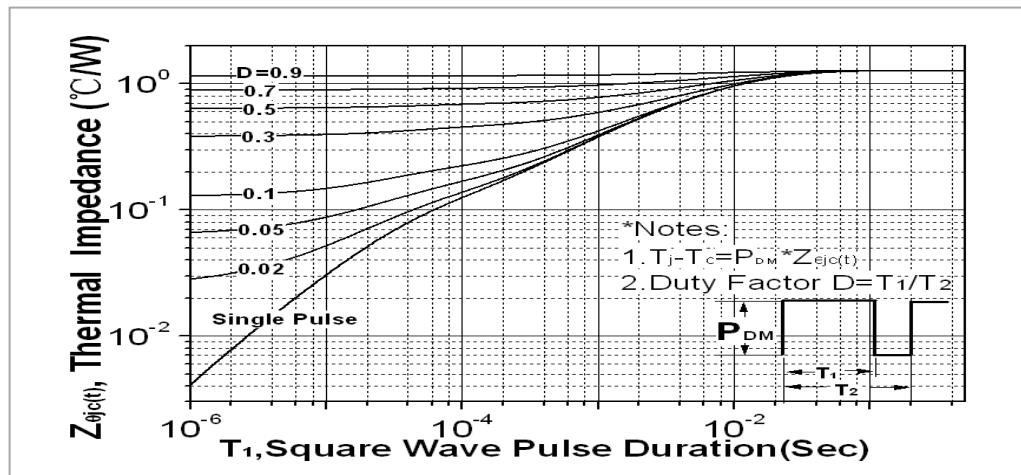


Fig. 13. Gate charge test circuit & waveform

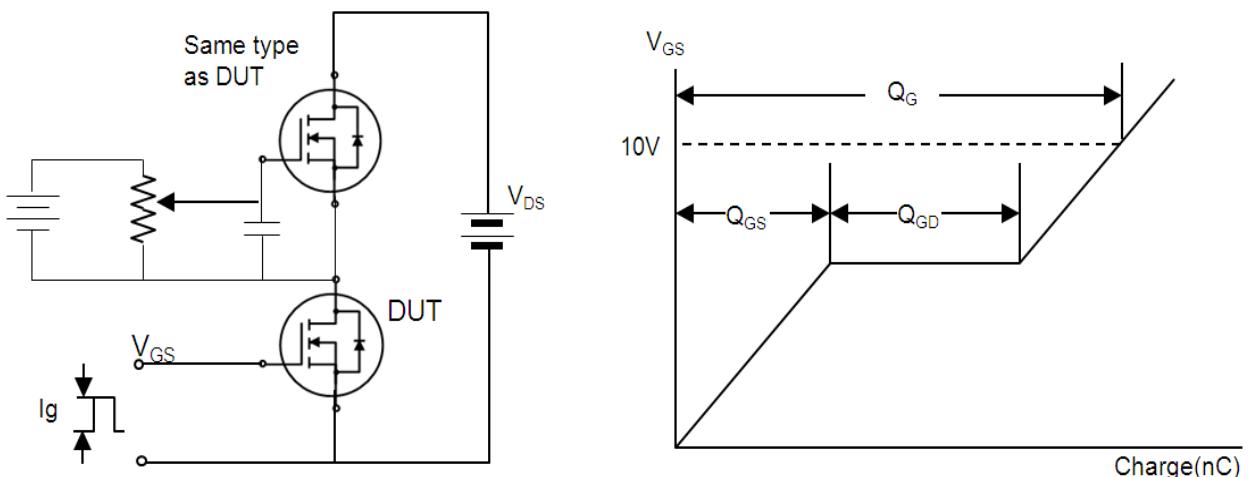


Fig. 14. Switching time test circuit & waveform

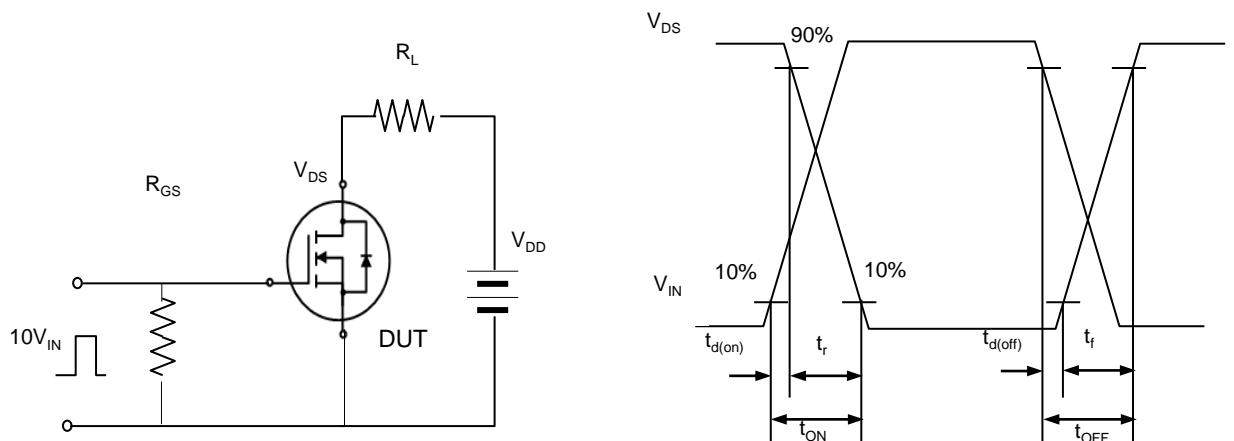


Fig. 15. Unclamped Inductive switching test circuit & waveform

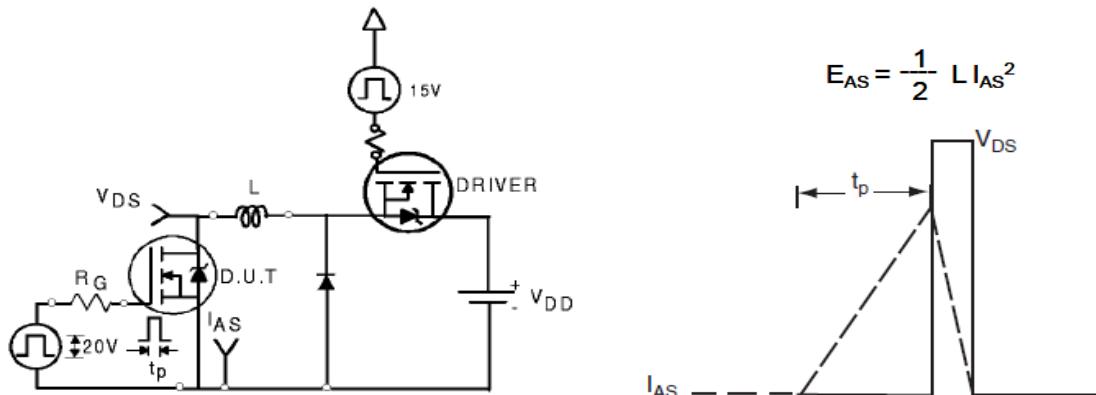
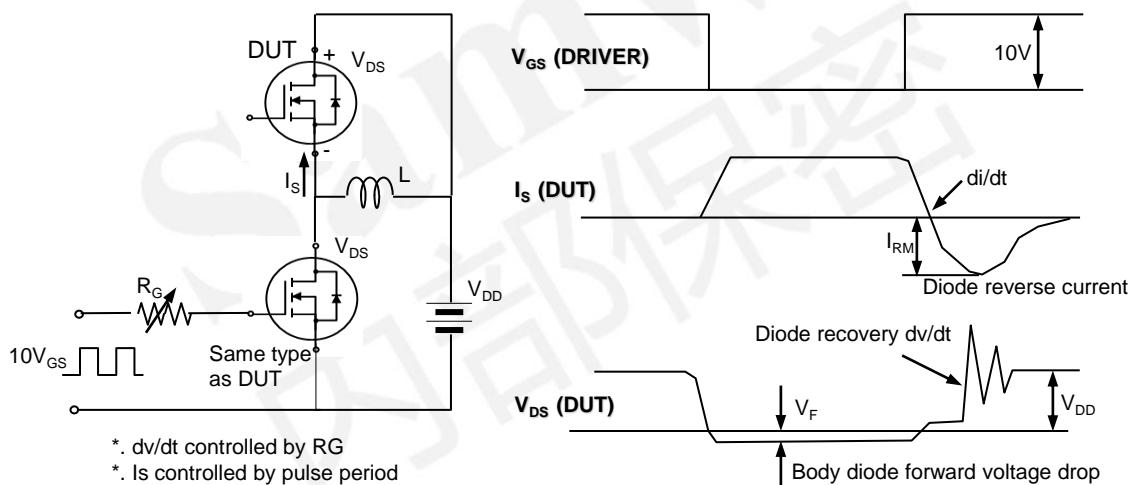


Fig. 16. Peak diode recovery dv/dt test circuit & waveform



### DISCLAIMER

- \* All the data & curve in this document was tested in SEMIPOWER TESTING & APPLICATION CENTER.
- \* This product has passed the PCT, TC, HTRB, HTGB, HAST, PC and Solderdunk reliability testing.
- \* Qualification standards can also be found on the Web site (<http://www.semipower.com.cn>)
- \* Suggestions for improvement are appreciated, Please send your suggestions to [samwin@samwinsemi.com](mailto:samwin@samwinsemi.com)

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